

Title (en)  
MEMS PACKAGING

Title (de)  
MEMS-SCHALTER UND DEREN VERPACKUNG

Title (fr)  
COMMUTATEURS MEMS ET LEUR CONDITIONNEMENT

Publication  
**EP 2499648 B1 20141029 (EN)**

Application  
**EP 10775878 A 20101110**

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Abstract (en)  
[origin: WO2011058354A1] A packaged RF MEMS device comprising: an RF MEMS device, a substrate upon which the RF MEMS device is mounted, a cover mounted on the substrate, the cover comprising a cavity for containing the RF MEMS device, the cover and substrate thereby defining a cover-to-substrate interface and a cover-to-substrate interface boundary, and at least one electrically conductive path extending between the RF MEMS device and a peripheral surface of the packaged MEMS device.

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